Package Outline Drawing
W4x4.16C
(WLCSP 0.5mm PITCH) WAFER LEVEL CHIP SCALE PACKAGE
Rev 1, 05/14

NOTES:
1. All dimensions are in millimeters.
2. Dimension and tolerance per ASME Y14.5M-1994, and JESD 95-1 SPP-010.
3. NSMD refers to non-solder mask defined pad design per Intersil Techbrief TB451.